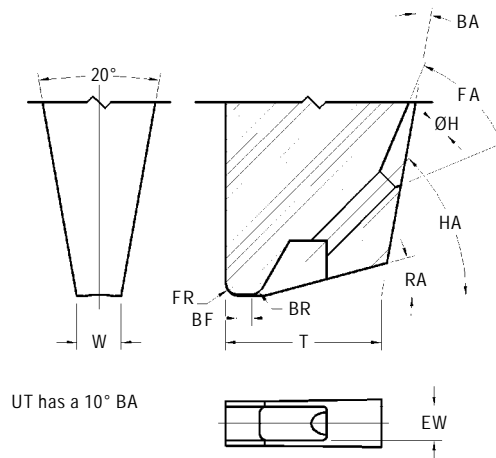
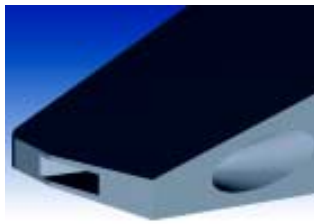
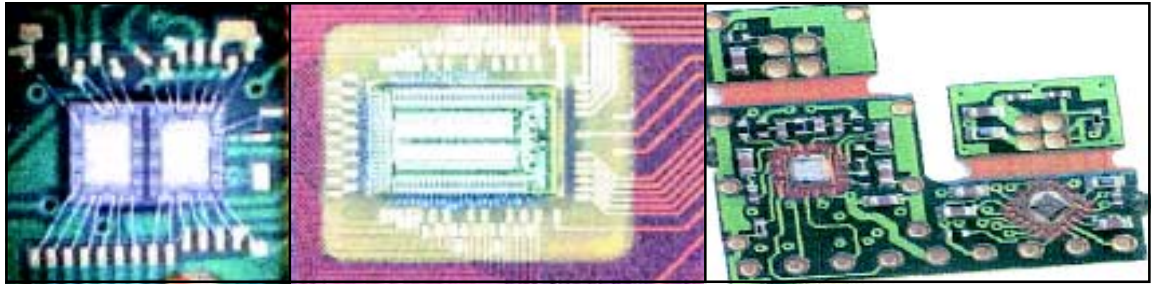


COB SERIES - CHIP-ON-BOARD AUTOBONDING TOOL

Chip-On-Board technology is successfully used to connect semiconductors to PCBs for high integration of electronic systems or microsystems. General conditions and procedures of chip and wire bonding are highly developed for standard applications, but new materials, increasing pin numbers, complex system integration processes and demands for higher reliability in low cost throw-away assemblies and more expensive profile-critical products has led to required improvements in the material, design and life of the tool.

SPT has developed tools in partnership with key OEM's to meet these demands



STANDARD DIMENSIONS								
Tool Styles	Wire Feed Angle	Hole / Bond Flat	Hole H in / μm $\pm .0002/5$	Bond Flat BF in / μm $\pm .0002/5$	Foot Width W in / μm $\pm .0002/5$	Exit Width EW in / μm $\pm .0002/5$	Tip Thickness T in / μm $\pm .0002/5$	Useable Wire Diameter in / μm
UT30A	30°	2020	.0020 / 51	.0020 / 51	.0040 / 102	.0020 / 51	.0150 / 381	.0010 / 25 through .0013 / 33
		2025	.0020 / 51	.0025 / 64	.0040 / 102	.0020 / 51	.0150 / 381	
		2520	.0025 / 64	.0020 / 51	.0040 / 102	.0020 / 51	.0150 / 381	
		2525	.0025 / 64	.0025 / 64	.0040 / 102	.0020 / 51	.0150 / 381	.0013 / 33 through .0015 / 38
		3020	.0030 / 76	.0020 / 51	.0050 / 127	.0030 / 76	.0200 / 508	
		3025	.0030 / 76	.0025 / 64	.0050 / 127	.0030 / 76	.0200 / 508	
		3030	.0030 / 76	.0030 / 76	.0050 / 127	.0030 / 76	.0200 / 508	
		3035	.0030 / 76	.0035 / 89	.0050 / 127	.0030 / 76	.0200 / 508	

COB SERIES - GENERAL GUIDELINES ON HOW TO ORDER

STYLE		FEED ANGLE
UT	UNIVERSAL BONDING TOOL	30°

RADIUS SET	Wire Material	Wire Diameter	Hole Size	FR ± .0001/3	BR ± .0001/3
A	Aluminum	.0010 / 25 - .0013 / 33	.0020/51 - .0025/64	.0010 / 25	.0010 / 25
A	Aluminum	.0013 / 33 - .0015 / 38	.0030 / 76	.0015 / 38	.0015 / 38

MATERIAL	HOLE / BOND FLAT	TOOL LENGTH (TL)
W Tungsten Carbide Ultra Fine Grain for Aluminum Wire	Will rely on specific application requirements (wire diameter used, bond pad size) – see dimension Table	S = .437 / 11.1 mm ¾ = .750 / 19.05 mm L = .828 / 21.0 mm 1.00 = 1.00 / 25.4 mm Longer lengths are available consult Bonder manufacturer for specifications.

FOOT OPTIONS	
CM	Concave foot design with FR, BR and BF matte (for Aluminum and Gold wire)

HOW TO ORDER	
SPECIFY	Style/Radius Set – Material – Hole/Bond Flat – Tool Length – Foot Option (For modifications to standard tools, use part number and specify modified dimensions) or contact our technical support staff for assistance with your requirements. For Special Shank Style refer to page 61.
EXAMPLE	UT30A - 2520 - L UT30A - 2020 - ¾